SIGC25T60UN

High Speed IGBT Chip in NPT-technology

FEATURES:

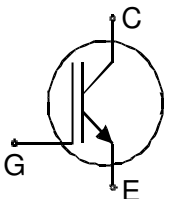
- **low Eoff**
- 600V NPT technology
- 100µm chip
- short circuit prove
- positive temperature coefficient
- easy paralleling

This chip is used for:

- SGP30N60HS

Applications:

- Welding
- PFC
- UPS



Chip Type	V_{CE}	I_{Cn}	Die Size	Package	Ordering Code
SIGC25T60UN	600V	30A	4.5 x 5.71 mm^2	sawn on foil	Q67041-A4667-A001

MECHANICAL PARAMETER:

Raster size	4.5 x 5.71	mm^2
Area total / active	25.7 / 20.7	
Emitter pad size	2x(2.18x1.58)	
Gate pad size	1.08 x 0.68	
Thickness	100	µm
Wafer size	150	mm
Flat position	90	deg
Max.possible chips per wafer	566	
Passivation frontside	Photoimide	
Emitter metallization	3200 nm Al Si 1%	
Collector metallization	1400 nm Ni Ag –system suitable for epoxy and soft solder die bonding	
Die bond	electrically conductive glue or solder	
Wire bond	Al, ≤500µm	
Reject Ink Dot Size	∅ 0.65mm ; max 1.2mm	
Recommended Storage Environment	store in original container, in dry nitrogen, < 6 month at an ambient temperature of 23°C	

Edited by INFINEON Technologies AI PS DD HV3, L 7262-U, Edition2, 28.11.2003

SIGC25T60UN

MAXIMUM RATINGS:

Parameter	Symbol	Value	Unit
Collector-emitter voltage, T_j=25 °C	V_{CE}	600	V
DC collector current, limited by T_{jmax}	I_C	1)	A
Pulsed collector current, t_p limited by T_{jmax}	I_{cpuls}	90	A
Gate emitter voltage	V_{GE}	±20	V
Operating junction and storage temperature	T_j, T_{stg}	-55 ... +150	°C

1) depending on thermal properties of assembly

STATIC CHARACTERISTICS (tested on chip), T_j=25 °C, unless otherwise specified:

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
Collector-emitter breakdown voltage	$V_{(BR)CES}$	V_{GE}=0V, I_C=500µA	600			V
Collector-emitter saturation voltage	$V_{CE(sat)}$	V_{GE}=15V, I_C=30A		2.8	3.15	
Gate-emitter threshold voltage	$V_{GE(th)}$	I_C=300µA, V_{GE}=V_{CE}	3	4	5	
Zero gate voltage collector current	I_{CES}	V_{CE}=600V, V_{GE}=0V			2	µA
Gate-emitter leakage current	I_{GES}	V_{CE}=0V, V_{GE}=20V			120	nA

DYNAMIC CHARACTERISTICS (tested at component):

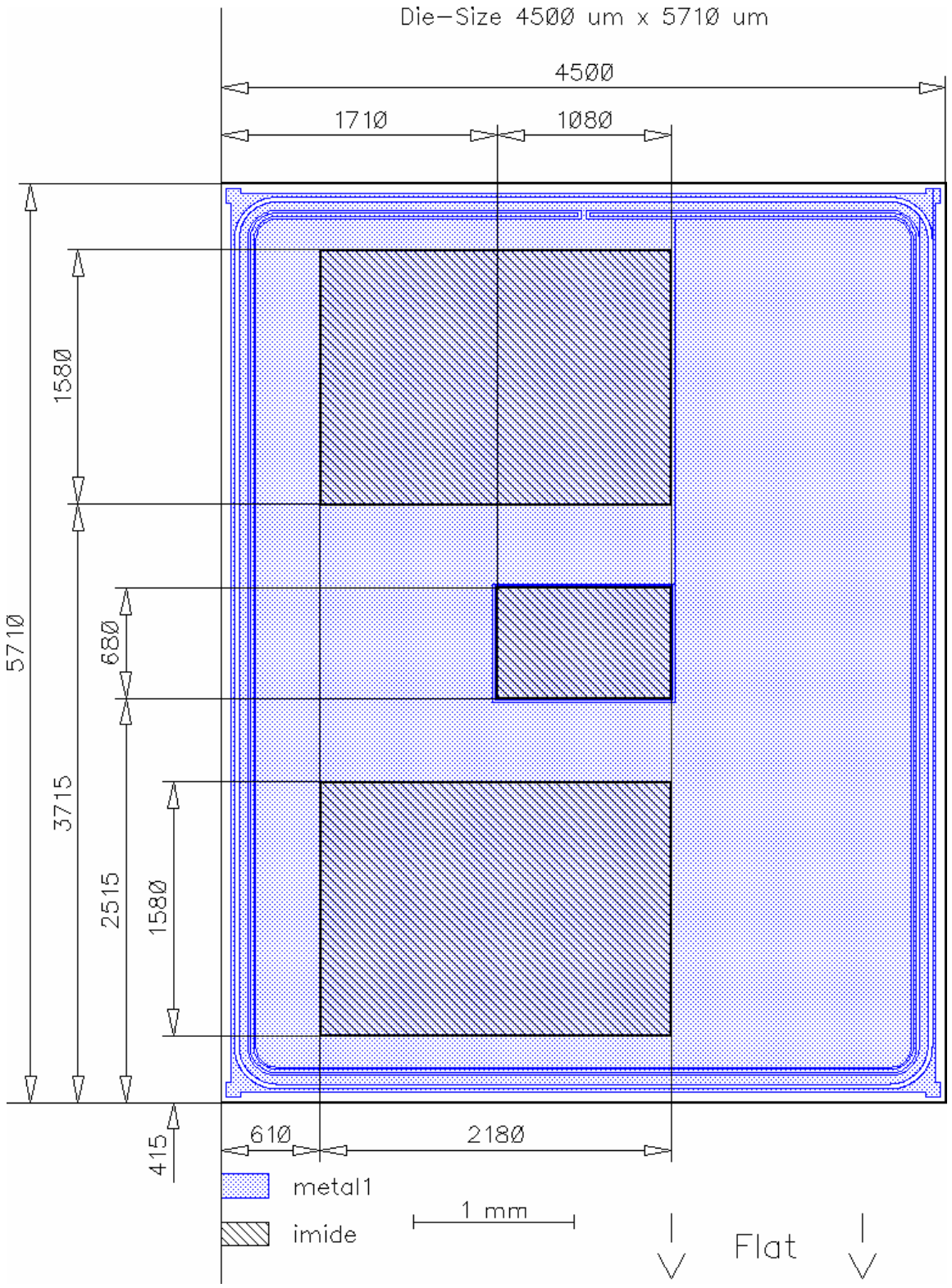
Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
Input capacitance	C_{iss}	V_{CE}=25V V_{GE}=0V f=1MHz	-	1500		pF
Output capacitance	C_{oss}		-	150		
Reverse transfer capacitance	C_{rss}		-	92		

SWITCHING CHARACTERISTICS (tested at component), Inductive Load:

Parameter	Symbol	Conditions 1)	Value			Unit
			min.	typ.	max.	
Turn-on delay time	$t_{d(on)}$	T_j=150°C V_{CC}=400V I_C=30A V_{GE}=+15/0V R_G=1.8Ω	-	16		ns
Rise time	t_r		-	13		
Turn-off delay time	$t_{d(off)}$		-	122		
Fall time	t_f		-	29		

1) values also influenced by parasitic L- and C- in measurement and package.

CHIP DRAWING:



SIGC25T60UN

FURTHER ELECTRICAL CHARACTERISTICS:

This chip data sheet refers to the device data sheet	SGP30N60HS	Package :TO220

Description:

AQL 0,65 for visual inspection according to failure catalog

Electrostatic Discharge Sensitive Device according to MIL-STD 883

Test-Normen Villach/Prüffeld

Published by
Infineon Technologies AG,
Bereich Kommunikation
St.-Martin-Strasse 53,
D-81541 München

Attention please!

The information herein is given to describe certain components and shall not be considered as warranted characteristics.

Terms of delivery and rights to technical change reserved.

We hereby disclaim any and all warranties, including but not limited to warranties of non-infringement, regarding circuits, descriptions and charts stated herein.

Infineon Technologies is an approved CECC manufacturer.

Information

For further information on technology, delivery terms and conditions and prices please contact your nearest Infineon Technologies Office in Germany or our Infineon Technologies Representatives world-wide (see address list).

Warnings

Due to technical requirements components may contain dangerous substances. For information on the types in question please contact your nearest Infineon Technologies Office.

Infineon Technologies components may only be used in life-support devices or systems with the express written approval of Infineon Technologies, if a failure of such components can reasonably be expected to cause the failure of that life-support device or system, or to affect the safety or effectiveness of that device or system. Life support devices or systems are intended to be implanted in the human body, or to support and / or maintain and sustain and / or protect human life. If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.